

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	14672	solder near2 (ball\$8 bump\$6)	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/09 08:58
L2	977	L1 same flux\$6	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/09 08:58
L3	186	L2 and (wafer semiconductor chip die dice) and ((active adj surface) pad underbump (under adj bump))	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/09 08:58
L4	21516	solder near2 (ball\$8 bump\$6)	US-PGPUB; USPAT	OR	ON	2005/05/09 10:11
L5	1889	L4 with flux\$6	US-PGPUB; USPAT	OR	ON	2005/05/09 09:18
L6	565	L5 same (wafer semiconductor chip die dice) same ((active adj surface) pad underbump (under adj bump))	US-PGPUB; USPAT	OR	ON	2005/05/09 09:18
L7	5971	438/108.ccls. 438/612.ccls. 438/613.ccls. 438/614.ccls. 257/738.ccls. 257/e21.508.ccls. 29/842.ccls.	US-PGPUB; USPAT	OR	ON	2005/05/09 11:30
L8	240	L7 and L6	US-PGPUB; USPAT	OR	ON	2005/05/09 09:18
L9	359	L5 same (wafer semiconductor chip die dice) same ((active adj surface) pad) same (underbump (under adj bump) passivat\$6 reflow\$6)	US-PGPUB; USPAT	OR	ON	2005/05/09 09:40
L10	21516	solder near2 (ball\$8 bump\$6)	US-PGPUB; USPAT	OR	ON	2005/05/09 10:05
L11	35	L10 with flux\$6 with solid	US-PGPUB; USPAT	OR	ON	2005/05/09 10:05
L12	3768	7 and 10	US-PGPUB; USPAT	OR	ON	2005/05/09 11:18
L13	1	"6638847".pn.	US-PGPUB; USPAT	OR	ON	2005/05/09 11:18
L14	1179	438/615.ccls. 228/180.22.ccls.	US-PGPUB; USPAT	OR	OFF	2005/05/09 11:31
L15	234	5 and 14	US-PGPUB; USPAT	OR	ON	2005/05/09 11:44
L16	183	15 not 8	US-PGPUB; USPAT	OR	ON	2005/05/09 11:32
L17	86	6 and 14	US-PGPUB; USPAT	OR	ON	2005/05/09 11:33